Appln. No.: 10/776,473

Amndt. dated September 8, 2005

Reply to Office Action of April 8, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A metal alloy-metallic thermal barrier coating comprising

an alloy metal and greater than about 4 atomic % of at least one P-group alloying element,

wherein said metal thermal barrier coating has a thermal conductivity equal to or less than about

10 W/m-K at 400 degrees Celsius.

2. (Currently Amended) A metal alloy The metallic thermal barrier coating of claim

1 wherein the P-group alloying element is present at a level of 4 atomic % to 50 atomic %.

3. (Currently Amended) The metal alloy metallic thermal barrier coating of claim 1

wherein said P-group alloying element is selected from the group consisting of carbon, nitrogen,

phosphorous, silicon, boron, and mixtures thereof.

4. (Currently Amended) A metal alloy The metallic thermal barrier coating

according to claim 1, wherein said at least one P-group alloying element comprises 16.0 atomic

% B, 4.0 atomic % C, and 5.0 atomic % Si.

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5. (Currently Amended) A metal alloy The metallic thermal barrier coating

according to claim 1 wherein the alloy metal is selected from the group consisting of iron,

chrome, molybdenum, tungsten, manganese, cobalt, nickel, copper, and mixtures thereof.

6. (Currently Amended) A method for reducing the thermal and/or electrical

conductivity producing a metallic thermal barrier coating of a metal alloy composition

comprising:

(a) supplying a metal alloy composition; and

(b) supplying a P-group alloying element;

(c) mixing said metal alloy composition and said P-group alloying element wherein

said P-group alloying element is present at a level to reduce the thermal/and or electrical

conductivity of said metal alloy composition, wherein said metal alloy has a thermal conductivity

equal to or less than about 10 W/m-K at 400 degrees Celsius.

7. (Currently Amended) A method of reducing the thermal and/or electrical

conductivity producing a metallic thermal barrier coating of a metal alloy composition

comprising:

(a) supplying a base metal with a free electron density

(b) supplying a P-group alloying element

(c) combining said P-group alloying element with said base metal and decreasing the

free electron density of the base metal, wherein said metal alloy has a thermal conductivity equal

to or less than about 10 W/m-K at 400 degrees Celsius.

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8. (Original) The method of claim 7 wherein the free electron density of the base

metal is reduced from its base metal value, and wherein said free electron density is generally

representative of a fully filled outer shell after combination with said P-group alloying element.

9. (Original) The method of claim 7 wherein said P-group alloying element is

selected from the group consisting of carbon, nitrogen, phosphorous, silicon, boron, and mixtures

thereof.

10. (Currently Amended) The method of claim 7 wherein the base metal is selected

from the group consisting of iron, nickel, cobalt, aluminum, copper, zinc[[.]], titanium,

zirconium, niobium, molybdenum, tantalum, vanadium, hafnium, tungsten, manganese, and

combinations thereof.